

Description

EW 6326 is a one-part, solvent free epoxy. It can be cured at low temperatures and provide excellent bonding strength to various substrates, especially for stainless steel to magnets.

Features

- Recommended substrates: glass, aluminum, stainless steel, FPC and PCB
- Low temperature curing
- Fast curing speed

Uncured Properties

Chemical Type	Epoxy
Appearance	Black
Viscosity @ 25°C [mPa·s] Brookfield DV2T, spindle 14# @ 5rpm	23,000
Specific Gravity [g/cm³]	~1.1
Shelf Life @ -40±5°C [months]	6
Pot Life @ 25°C [hrs]	48

Curing Conditions

Thermal Curing @ 60°C [mins]	30
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Cured Properties

Hardness [Shore D] ASTM D2240	75
Shear Strength [MPa] PCB/PCB ASTM D1002	15
Tensile Strength [MPa] ASTM D638	27
Elongation at Break [%] ASTM D638	4.7
Glass Transition Temperature (Tg) [°C] ISO 11359	55

Coefficient of Thermal Expansion (CTE) [ppm/K] Below Tg Above Tg ASTM D696	101 188
Surface Resistivity [ohm·cm] ASTM D257	>1.0x10 ¹⁵
Volume Resistivity [ohm·cm] ASTM D257	>1.0x10 ¹⁵
Dielectric Strength [V/mil] ASTM D149	300
Water Absorption [%] ASTM D570	0.2

Directions for Use

1. Surface Treatment

Surfaces to be bonded should be free of dust, oil, grease or any other contaminants in order to achieve a reproducible bond. For slightly contaminated surfaces, it is sufficient to wipe with isopropanol or ethanol. Substrates with a low surface energy (e.g. polyethylene, polypropylene, Teflon) need to be pre-treated physically (e.g. atmospheric plasma or corona) in order to achieve sufficient adhesion.

2. Application

Products are supplied ready for use. Depending on package type, they can be dosed manually, semi-automatically or fully-automatically with a dosage apparatus. With automatic dispensing using a cartridge, the adhesive is conveyed via pressure and a piston rod to a dispense valve. With bottles, the adhesive is conveyed using a pump.

After application, it is recommended that the two substrates be adjoined immediately as it is possible the curing process will begin with select products under ambient conditions.

3. Suggested working temperature range is -40 to 150°C.

Storage

Maximum shelf life may be obtained when product is stored in a cool, dry location at a temperature of **-40±5°C**.

TO PREVENT CONTAMINATION OF UNUSED PRODUCT, DO NOT RETURN ANY PRODUCT TO ITS ORIGINAL CONTAINER.

Allow the product to thaw for two hours (30g/package) or four hours (300g/package) after it is removed from the refrigerator prior to use. It is best practice to wipe away any moisture on the surface of the syringe with cleanroom wipes.

Materials Handling

Refer to the Material Safety Data Sheet (MSDS) for this product.

Disclaimer

The information provided here including the recommendations for use and application of the product is based on internal laboratory test conditions and should only be used as a reference. CollTech does not assume responsibility for the test or performance results obtained by the user. It is the responsibility of the user to perform their own evaluations to confirm whether this product is suitable for their application.